What is claimed is:

1. A printed wiring board comprising:

a printed wiring substrate having a plurality of a wiring layer, and

a thermal expansion buffering sheet having a lower coefficient of thermal expansion than that of said printed wiring substrate, which is integrally laminated on a surface of said printed wiring substrate.

2. A printed wiring board according to claim 1, wherein a coefficient of thermal expansion of said printed wiring substrate is 13 to 20 ppm, and a coefficient of thermal expansion of said thermal expansion buffering sheet is 6 to 12 ppm.

3. A printed wiring board according to claim 1, wherein said printed wiring substrate is a multi-layer wiring board which laminates wiring layers and insulation layers which are made of a glass cloth impregnated with an epoxy resin, alternately.

4. A printed wiring board according to claim 1, wherein said thermal expansion buffering sheet is made of an aramid.

5. A printed wiring board according to claim 1, wherein an electrode pattern so as to connect a part to be mounted on a surface of said printed wiring board is provided on a surface of said thermal expansion buffering sheet.

6. A printed wiring board according to claim 5, wherein said part to be mounted on said surface of said printed wiring board is connected to said electrode pattern via a solder ball.

7. A printed wiring board comprising:

a multi-layer wiring section which laminates wiring layers and insulation layers alternately,

a thermal expansion buffering sheet having a lower coefficient of thermal expansion than that of said multi-layer wiring section, which is integrally laminated on a surface of said multi-layer wiring section.

8. A printed wiring board comprising:

a multi-layer wiring section which laminates wiring layers and insulation layers alternately,

a thermal expansion buffering sheet having a lower coefficient of thermal expansion than that of said multi-layer wiring section, which is integrally laminated on a surface of said multi-layer wiring section, and

an electrode pattern provided on a surface of said thermal expansion buffering sheet so as to connect a part to be mounted on a surface of said printed wiring board.

9. A printed wiring board comprising:

a multi-layer wiring section which laminates wiring layers and insulation layers alternately,

a thermal expansion buffering sheet, a material of which is aramid, having a lower coefficient of thermal expansion than that of said multi-layer wiring section, which is integrally laminated on a surface of said multi-layer wiring section.

10. A printed wiring board comprising:

a multi-layer wiring section which laminates wiring layers and insulation layers alternately,

a thermal expansion buffering sheet, a material of which is aramid, having a lower coefficient of thermal

expansion than that of said multi-layer wiring section, which is integrally laminated on a surface of said multi-layer wiring section, and

an electrode pattern provided on a surface of said thermal expansion buffering sheet so as to connect a part to be mounted on a surface of said printed wiring board.